

1A Avg.

30 Volts

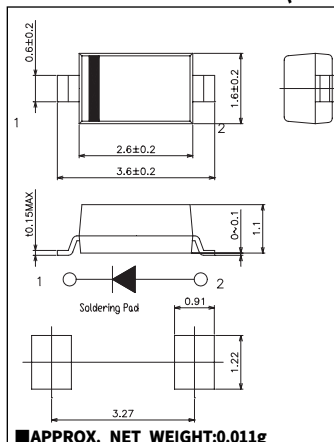
SBD

EP10HY03

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	30	V
直 流 順 電 流 Direct Forward Current	I_{DC}	$T_I=120^{\circ}\text{C}$ T_I :Lead Temperature $T_a=34^{\circ}\text{C}^*$	1.0 A
平 均 整 流 電 流 Average Rectified Forward Current	I_o	$T_I=125^{\circ}\text{C}$ VRM=0V T_I :Lead Temperature $T_a=35^{\circ}\text{C}^*$ VRM=0V	0.7 A
サージ順電流 Surge Forward Current	I_{FSM}	12 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	$-40\sim+150$	$^{\circ}\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	$-40\sim+150$	$^{\circ}\text{C}$

■OUTLINE DRAWING(mm)



■電気的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}\text{C}$, $V_{RM}=V_{RRM}$	—	—	0.5	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}\text{C}$, $I_{FM}=1\text{A}$	—	—	0.56	V
熱 抵 抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間* Junction to Ambient*	—	—	270	$^{\circ}\text{C}/\text{W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	70	$^{\circ}\text{C}/\text{W}$

*プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands=1×1 mm, Both Sides)
(T_I : Lead Temperature)

■定格・特性曲線

FIG.1

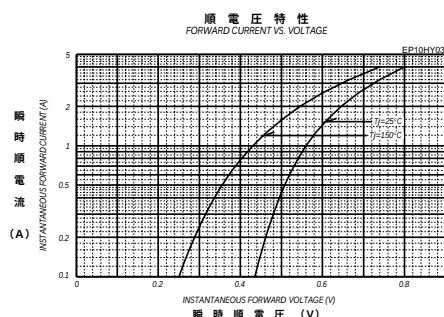


FIG.2

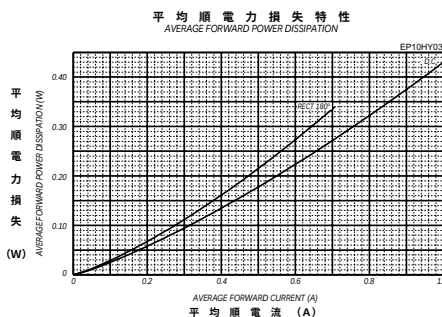


FIG.3

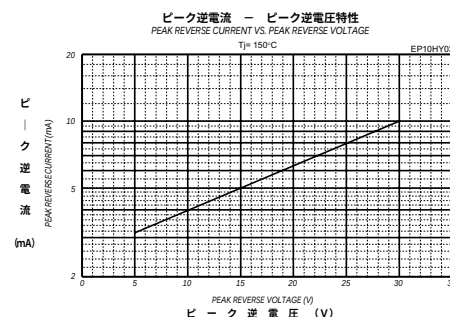


FIG.4

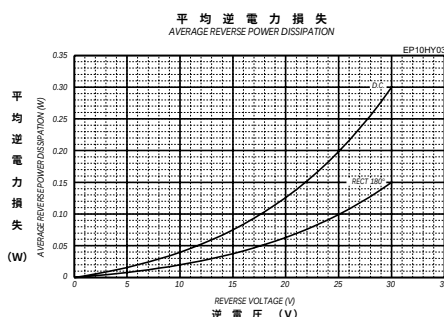


FIG.5

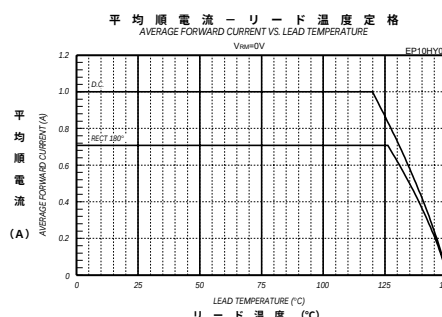


FIG.6

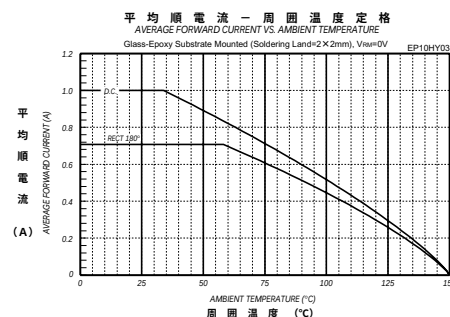


FIG.7

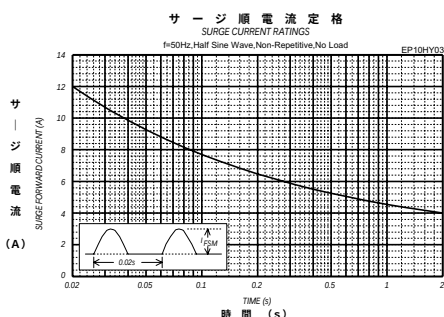


FIG.8

